



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Claire RICHTARCH

Confirmation No.6886

Application No: 10/671,812

Group Art Unit: 1762

Filing Date: September 25, 2003

Examiner:

For: METHOD OF PREPARING A SURFACE  
OF A SEMICONDUCTOR WAFER TO  
MAKE IT EPIREADY

Atty. Docket No.: 4717-11300

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Pursuant to applicants' duty of disclosure under 37 C.F.R. 1.56, enclosed is a PTO form 1449 which lists four (4) cited references for the Examiner's review and consideration. A copy of the Preliminary Search Report is enclosed.

It is respectfully requested that these references be made of record in this application by the Examiner's completion and return of the PTO Form 1449.

No fee or certification is believed to be due for this submission since the filing of this statement is being submitted prior to the issuance of the first office action for this application. Should any fees be required, however, please charge such fees to **Winston & Strawn LLP** Deposit Account No. 50-1814.

Respectfully submitted,

A handwritten signature in dark ink, appearing to read "Allan A. Fanucci".

Allan A. Fanucci (Reg. No. 30,256)

**WINSTON & STRAWN LLP**  
**CUSTOMER NO. 28765**

Date: May 7, 2004

Enclosures

(212) 294-3311

<b>LIST OF REFERENCES CITED BY APPLICANT</b> <b>Form PTO-1449</b> <i>(Use several sheets if necessary)</i>				ATTY. DOCKET NO.: 4717-11300		APPLICATION NO.:	
				APPLICANT: Claire RICHTARCH			
				FILING DATE: September 25, 2003		GROUP:	

  

U.S. PATENT DOCUMENTS							
*EXAMINER INITIAL	CITE	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,895,583	4/1999	Augustine et al.	216	53	

  

FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AB	0 966 034	12/1999	EPO			X	

  

OTHER REFERENCES <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>		
AC	Bruel, M. et al., "Smart-Cut": A Promising New SOI Material Technology, IEEE SOI Conference, October 1995, pp 178-179.	
AD	Maleville et al., "Wafer Bonding and H-Implantation Mechanisms Involved In The Smart-Cut Technology", Materials Science and Engineering, 1997, pp. 14-19.	

  

<b>EXAMINER</b>	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	A M
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